

SMAJ Plastic-Encapsulate Diodes

General Purpose Rectifier

Features

•l₀ 1A

●VRRM 50V-1000V

High surge current capability

Polarity: Color band denotes cathode

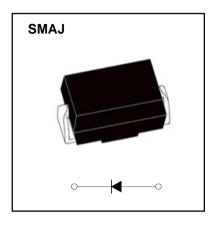
Applications

Rectifier

Marking

MX

X: From 1To 7



Limiting Values (Absolute Maximum Rating)

ltem	Symbol	Unit	Conditions	М						
			Conditions	1	2	3	4	5	6	7
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V		35	70	140	280	420	560	700
Average Forward Current	I _{F(AV)}	А	60Hz Half-sine wave, Resistance load, Ta=75°C	1						
Surge(Non-repetitive)Forward Current	I _{FSM}	А	60Hz Half-sine wave,1 cycle, Ta=25℃	30						
Junction Temperature	TJ	$^{\circ}$		-55~+125						
Storage Temperature	T _{STG}	$^{\circ}$		-55 ~ +150						

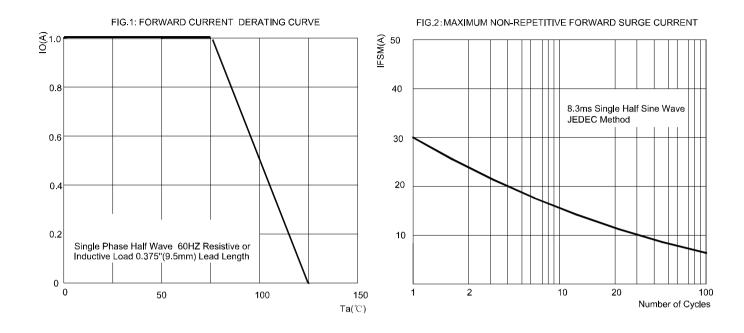
Electrical Characteristics (Ta=25°C Unless otherwise specified)

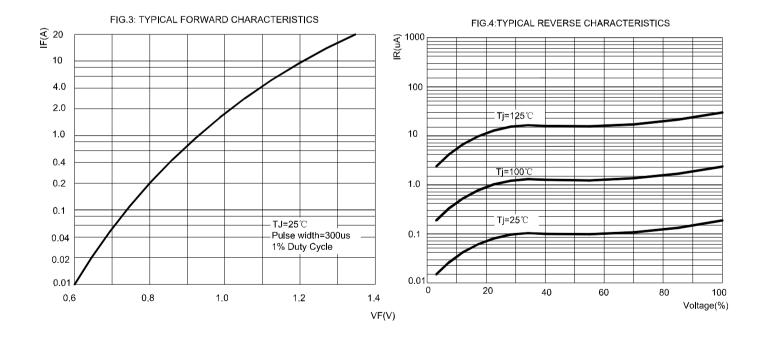
Item	Symbol	Unit	Test Condition		Мах
Peak Forward Voltage	V _{FM}	V	I _{FM} =1.0A		1.0
Peak Reverse Current	I _{RRM1}	μΑ	V _{RM} =V _{RRM}	T _a =25℃	5
	I RRM2			T _a =125℃	50
Thermal Resistance(Typical)	$R_{\theta J-A}$	°C/W	Between junction and ambient		55
	R _{θJ-L}	C/VV	Between junction and lead		25

Notes:

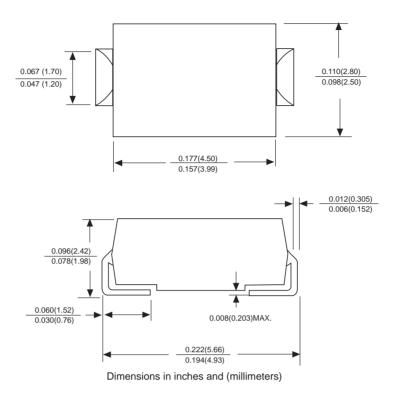
Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

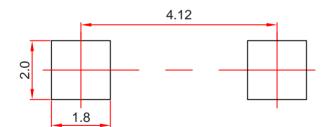




SMAJ Package Outline Dimensions



SMAJ Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSHD does not assume any liability arising out of the application or use of any product described herein.

High Diode Semiconductor

Reel Taping Specifications For Surface Mount Devices-SMA

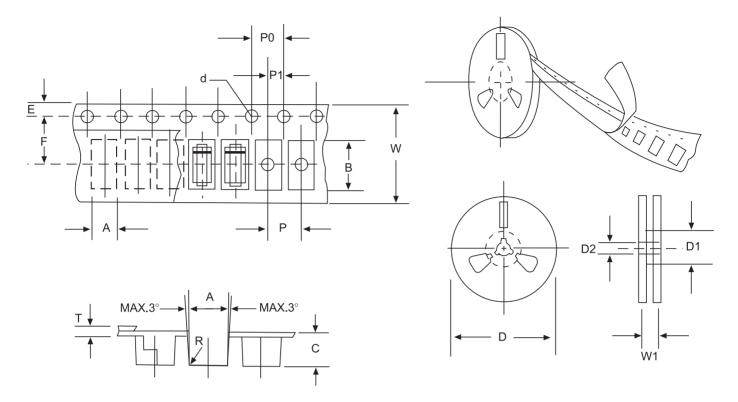


FIG: CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	В	5.33±0.1(0.210±0.004)
Carrier depth	С	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.5±0.05 (0.059±0.0002)
Reel outside diameter	D	330/178±2.0(13/7.0±0.79)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	Р	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	Т	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.